

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)			
KIYOFUMI SAKAGUCHI, ET AL.	·)	Examiner: Not Yet Assign		
Application No.: 10/085,046	;	Group Art Unit: 2813		
Filed: March 1, 2002	:			
For: PROCESS FOR PRODUCTION OF SEMICONDUCTOR SUBSTRATE	:) :)	September 5, 2002		

Commissioner for Patents Washington, D.C. 20231

Sir:

INFORMATION DISCLOSURE STATEMENT

In compliance with the duty of disclosure under 37 C.F.R. § 1.56 and in accordance with the practice under 37 C.F.R. §§ 1.97 and 1.98, the Examiner's attention is directed to the documents listed on the enclosed Form PTO-1449.

Applicants note that inclusion of documents in this statement does not constitute a representation that these documents are prior art. Moreover, Applicants wish to point out they have cited the references listed on the face of Matsushita, U.S. 5,811,348, Tayanaka 6,107,213 and Tayanaka 6,194,245. Applicants have copied claims from the Matsushita '348 patent in application no. 09/161,774 which Applicants understand has been forwarded to the Board for declaration of an interference. Claims from both the Tayanaka patents have been copied in the present application.

CONCLUSION

It is respectfully requested that the above information be considered by the Examiner and that a copy of the enclosed Form PTO-1449 be returned indicating that such information has been considered.

Applicants' undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should be directed to our address given below.

Respectfully submitted,

Attorney for Applicants

Registration No. 291767

FITZPATRICK, CELLA, HARPER & SCINTO 30 Rockefeller Plaza

New York, New York 10112-3801 Facsimile: (212) 218-2200

NY_Main241627 v1

PATENT APPLICATION

SEP 0 6 2002 E

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Ap	plication of:)	
KIYOFU	JMI SAKAGUCHI, ET AL.	;)	Examiner: Not Yet Assigned
Applicat	ion No.: 10/085,046)	Group Art Unit: 2813
Filed: M	arch 1, 2002	;	
For:	PROCESS FOR PRODUCTION OF SEMICONDUCTOR	;) ;	
	SUBSTRATE)	September 5 2002

Foreign documents cited in Information Disclosure Statement dated September 5, 2002

RECEIVED ROOM

SUBSTRATE

\$\$P 0	6 2007 S	IN THE UNITED STATES PAT	ENT	AND TRADEMARK OFFICE
TA TRADI	e Appl	ication of:)	Forming No. V. A.
	KIYOFUN	ИI SAKAGUCHI, ET AL.)	Examiner: Not Yet Assigned
	Applicatio	n No.: 10/085,046)	Group Art Unit: 2813
	Filed: Mar	ch 1, 2002	:	
	For:	PROCESS FOR PRODUCTION	:	

Other Publications cited in Information Disclosure Statement dated September 5, 2002

September 5, 2002

IC 5800 NAIL ROOM SEP -9 2002 RECEINED U.S. DEPARTMENT OF COMMERCE PE CONTROL O3500.010530.5

LIST OF REFERENCES CITED BY APPLICANT(S)
(Use several sheets if necessary)

SEP 0 6 2002

U.S. PATENT DOCKET NO.
03500.010530.5

APPLICATION NO.
WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

WW085,046

APPLICATION NO.

	THE STATE OF THE S	& TRADEMANTS	U.S. PATENT DOCUMENTS		-	7/
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	4,116,751	09/26/78	Zaromb	156	600	
	4,727,047	02/23/88	Bozler, et al.	437	89	
	5,248,621	09/28/93	Sano	437	3	
	5,250,460	10/05/93	Yamagata, et al.	437	62	
	5,277,748	01/11/94	Sakaguchi, et al.	156	630	
	5,278,092	01/11/94	Sato	437	90	
	5,278,093	01/11/94	Yonehara	437	109	
	5,285,078	02/08/94	Mimura, et al.	257	3	
	5,290,712	03/01/94	Sato, et al.	437	24	
	5,320,907	06/14/94	Sato	428	446	· · · · · · · · · · · · · · · · · · ·
	5,331,180	07/19/94	Yamada, et al.	257	3	
	5,362,683	11/08/94	Takenaka et al.	437	226	
	5,363,793	11/15/94	Sato	117	2	
	5,371,037	12/06/94	Yonehara	437	86	
	5,374,564	12/20/94	Bruel	437	24	
	5,403,771	04/04/95	Nishida, et al.	437	89	
	5,433,168	07/18/95	Yonehara	117	90	
	5,453,394	09/26/95	Yonehara, et al.	437	62	
	5,457,058	10/10/95	Yonehara	437	24	
	5,459,081	10/17/95	Kajita	437	3	<u> </u>
	5,466,631	11/14/95	Ichikawa, et al.	437	62	
KAMINER			DATE CONSIDERED			

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO 1449 (ATTY DOCKET NO. 03500.010530.5	APPLICATION NO.	10/085,046	
L	PATE	DEPARTMENT OF COMMERCES OF AND TRADEMARK OF TOE FERENCES CITED BY APPLICAN	P E CO	APPLICANT KIYOF	UMI SAKAGUCI	HI, ET AL.	and the state of t
	SEP 0 6 2002		FILING DATE March 1, 2	1002		313	
		EAT.	PADEMIAN U.S	. PATENT DOCUMENTS		000000	
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE
		5,536,361	07/16/96	Kondo et al.	156	630.1	
		5,644,156	07/01/97	Suzuki, et al.	257	485	
		5,670,411	09/23/97	Yonehara, et al.	437	62	
		5,811,348	09/22/98	Matsushita, et al.	438	455	
		5,854,123	12/29/98	Sato, et al.	438	507	
		5,856,229	01/05/99	Sakaguchi, et al.	438	406	
		5,863,830	01/26/99	Bruel, et al.	438	478	
		5,869,387	02/09/99	Sato, et al.	438	459	
		5,970,361	10/19/99	Kumomi, et al.	438	409	
		5,980,633	11/09/99	Yamagata, et al.	117	94	
		6,103,598	08/15/00	Yamagata, et al.	438	459	
		6,107,213	08/22/00	Tayanaka	438	762	
		6,121,117	09/19/00	Sato, et al.	438	459	
			FOREI	GN PATENT DOCUMENTS		,	, — — — — — — — — — — — — — — — — — — —
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO/ OR ABSTRACT
	EP	0417838 A1	09/06/90	ЕРО			
	EP	0469630 A2	02/05/92	ЕРО			
	EP	0499488A2	02/14/92	ЕРО			
	EP	0536790 A2	04/14/93	EP			
	EP	0553852 A2	08/04/93	ЕРО		``	
	EP	0553859 A3	08/04/93	ЕРО			
EXAMINER				DATE CONSIDERED			 _

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

′ 								
TO 1449 (m		TO THE OF COLUMN TERCE		ATTY DOCKET NO. 03500.010530.5	,	EICATION NO.	10/085,046	' <u> </u>
LIS	PATEN	DEPARTMENT OF COMMERCE NT AND TRADEMARK OFFICE FERENCES CITED BY APPLICAN	TI(S)	APPLICANT KI	IYOFUN	MI SAKAGU	JCHI, ETCAL	MARIAN
<u> </u>		Jse several sheets if necessar()	P 0 6 2002 말	FILING DATE March	1, 2002		WO P	2 7 2002
		Take the second	EIG	IN PATENT DOCUMENTS	····		0000000	1,/
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY		CLASS	SUBCLASS	TRANSLATION YESANO OR ABSTRACT
	EP	0553860 A2	08/04/93	ЕРО				
	EP	0554795 A1	08/93	ЕРО				
	EP	0584777 A1	02/02/94	ЕРО				
	EP	0618624 A2	10/05/94	EPO				
	ЕР	0757377 A2	02/05/97	ЕРО		. -	ļ	
	EP	0793263 A2	09/97	EPO				
	EP	0797258 A2	09/24/97	Europe				
	GB	2211991 A	07/12/89	Great Britain				
	JP	60 196955A	10/05/85	Japan				Abstract
	JP	62-108539	05/19/87	Japan				Abstract
	JP	62-279625	12/04/87	Japan				Part Tran.
	JР	03-70156	03/26/91	Japan				Abstract
	JP	05-211128	08/20/93	Japan				Abstract
	JP	05-283722 0	10/29/93	Japan				Translation
	JP	06-45622	02/18/94	Japan				Translation
	JP	07-79016	03/20/95	Japan				Abstract
	JP	07-211602	08/11/95	Japan				Abstract
	JP	07-302889	11/14/95	Japan				Abstract
	JP	07-326719	12/12/95	Japan				Abstract
EVANADED				DATE CONSIDERED				

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

to 144	U.S. DEPARTMENT OF COMMERCE		ATTY DOCKET NO. 03500.010530.5	5	APPLICATION NO.	10/085,046			
			APPLICANT KIYOFUMI SAKAGUÇHI, ET.AL.						
	Div	(Use several sheets if necessary)	P 0 6 2002	FILING DATE March			GROUP	2813 - Z	
		(A)	TRADEM PEREIG	GN PATENT DOCUMENTS			**************************************	, j	
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY		CLASS ,	SUBCLASS	TRANSLATION YES/NO/- OR ABSTRACT	
	JР	9-162090	06/20/97	Japan				Abstract	
	wo	92/09104	05/29/92	РСТ					
		OTHER D	OCUMENT(S) (Inclue	ding Author, Title, Date, Per	rtinent	Pages, Etc.)			
	\/ \/	T. Abe et al. "Silicon Kes partial translation)	sshou to Doping	g (Silicon Crystal an	nd Do	ping)", Maruze	n Co., Ltd., 1	986 (with	
	\ \ <u>\</u>	K. Barla, et al., "SOI Tec	chnology Using	g Bur <u>ied Layers of C</u>) O <u>xidiz</u>	zed Porous Si", j	p <u>p. 11-15 (19</u>	87)	
	/	H. Baumgart, et al., "Lig Abstracts, Elect. Chem. S			cteriza	ation Of Bonded	l SOI Wafers	", Extended	
	-	G.W. Cullen, ed., Journa			pp. <u>4</u> 2	 29-590, Oct. 199	——— 93 (see p. 547	.)	
	<i>\</i>	/	Extended Abstracts (the 57th Autumn Meeting, 1996); The Japan Society of Applied Physics (Abstr. 8a-V-						
	C	Extended Abstracts (The 44 th Spring Meeting, 1997); The Japan Society of Applied Physics and Related Societies (Abstr. 31a-B-5) (with translation)							
	V	Extended Abstracts (The 59 th Autumn Meeting, 1998); The Japan Society of Applied Physics (Abstr. 15a-YB-4) (with translation)							
		C. Harendt et al., "Silicon on Insulator material by Wafer Bonding," Journal of Materials, vol. 20, no. 3, pp. 267-77, March 1991.							
	Y. Hashimoto, "Shin-Kagaku Yougo Jiten" (new chemical term dictionary), Sankyo Shuppan Co., Ltd., 6 th Edn (1973) (definition of anodic oxidation) (with translation)								
	_	R.P. Holmstrom, "Comp porous silicon," Applied					ping formati	on of oxidized	
	V	C.E. Hunt, et al., "Thinni Soc. 1st Symp., pp. 165-73	-	Waters: Etch-Stop /	Appr	oaches", Extend	led Abstracts	, Elect. Chem.	
		K. Imai, "A New Dielecti 159-64, 1981.	ric Isolation M	ethod Using Porous	Silico	on," Solid State	Electronics,	vol. 24, pp.	
	*	K. Imai et al., "Crystallii <u>63</u> , 547-553 (1983)	ne Quality of S	ilicon Layer Former	d by l	FIPOS Technolo	ogy," <u>J. of Cr</u>	ystal Growth	
EXAMINER									

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO 1449 (modified)	ATTY DOCKET NO. 03500.010530.5	APPLICATION NO. 10/085,046						
U.S. DEPARTMENT OF COMMERCE PE	APPLICANT							
LIST OF REFERENCES CITED BY APPLICANT(S) (Use several sheets if necessary) SEP 0 6 2002	KIYOFU FILING DATE	MI SAKAGUCHI, ET AL.						
\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	March 1, 200							
ONER DOCUMENTS (S) (Including Author, Title, Date, Pertinent Pages, Etc.)								
T. Ito et al. "Porous Silicon Crysta (1988) (no translation)	T. Ito et al. "Porous Silicon Crystal Prepared by Anodization", <u>Applied Physics</u> (Japanese) vol. 57 no. 11 (1988) (no translation)							
V. Labunov, "Heat Treatment Effe	ect on Porous Silicon," Thin	Solid Films, 137 (1986) 123-134						
W.P. Maszara, "Silicon-On-Insulat 1,pp. 340-47 (1991)	tor by Wafer Bonding: A Re	eview", J. Electrochem. Soc., vol. 138, No.						
Kazutoshi Nagano, et al., "Oxidize Matsushita Electric Industrial Co.,		plication", Semiconductor Research Lab						
Nikkei Microdevice, pp. 76-77 (199	94) (with translation)							
K. Ogasawara, et al., "Enhanceme Photoelectrochemical Behavior", J	nt of Electroluminescence fr J. Electrochem. Soc., vol. 142	om n-Type Porous Silicon and Its 2, no. 6, pp.1874-79 (1995)						
Hole Spacing Technique", Record	M. Ohnishi, et al., "New Type Structures Of A-Si Solar Cell Submodules Fabricated By Microscopic							
Patent Abstracts of Japan, vol. 18,	No. 066 (E-1501), Feb. 3, 19	94.						
V. Raineri, et al., "Silicon-on-insul: Phys. Lett. 66(26), 3653-3656 (June		plantation and thermal oxidation", Appl.						
Sato, Extended Abstracts, Elect. C		i-06 (1994).						
H. Tayanaka, et al., "Thin-Film Ci Silicon Sacrificial Layer" 2d Work (1998)	H. Tayanaka, et al., "Thin-Film Crystalline Silicon Solar Cells Obtained by Separation of a Porous Silicon Sacrificial Layer" 2d World Conf. and Exhibition on Photovoltaic Solar Energy Conversion							
T. Unagami, "Formation Mechanic of the Electrochemical Society, vol	T. Unagami, "Formation Mechanism of Porous Silicon Layer by Anodization in HF Solution," Journal of the Electrochemical Society, vol. 127, no. 2, pp. 476-83, Feb. 1980.							
A. Uhlir, Jr., "Electrolytic Shaping XXXV, pp. 333-47, Mar. 1956.	A. Uhlir, Jr., "Electrolytic Shaping of Geranium and Silicon," The Bell System Technical Journal, vol.							
A. Van Veen, et al., "Helium-Induc vol. 107, pp. 449-54 (1988)	A. Van Veen, et al., "Helium-Induced Porous Layer Formation In Silicon", Mat. Res. Soc. Symp. Proc.							
	T. Yasumata, et al., "Ultrathin Si films grown expitaxially on porous silicon", Applied Surface Science,							
	T. Yonehara et al., "Epitaxial layer transfer by bond and etch back of porous Si", Appl. Phys. Lett.							
EXAMINER	DATE CONSIDERED							

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.